June 2014

FSA641 — 2:1 MIPI Switch, Featuring 2-Data and 1-Data Lane Configuration

Features

- Switch Type: 2:1
- Signal Types MIPI, DPHY
- V_{CC}: 2.65 to 4.3 V
- Input Signals 0 to V_{CC}
- R_{ON}:
  - 7 Ω Typical HS MIPI
  - 10 Ω Typical LS MIPI
- ΔR_{ON}: 0.75 Ω Typical HS & LS MIPI
- I_{CC}: 1 µA Maximum
- O_{IRR}: -50 dB Typical
- X_{TALK}: -40 dB Typical
- Bandwidth: 1 GHz Typical
- Channel-to-Channel Skew: 15 ps Typical
- C_{ON}: 8 pF Typical
- Package 20-Lead UMLP

Applications

- Cellular Phones, Smartphones
- Displays

Description

The FSA641 is a 2:1 MIPI switch made for 2-data lane and 1-data lane modules. This part is configured as a single-pole, double-throw switch (SPDT) and is optimized for switching between two high-speed or low-power MIPI sources. The FSA641 has specially been designed for the MIPI specification and allows connection to either a CSI or DSI module. The FSA641 features an extremely low on capacitance (C_{ON}) of 8 pF. The wide bandwidth (1 GHz) results in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk minimizes interference.

Related Resources

- For samples and questions, please contact: Analog.Switch@fairchildsemi.com.
- FSA641 Demonstration Board

Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSA641UMX	F641	-40 to +85°C	20-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 3.0 x 3.0 mm

Typical Application

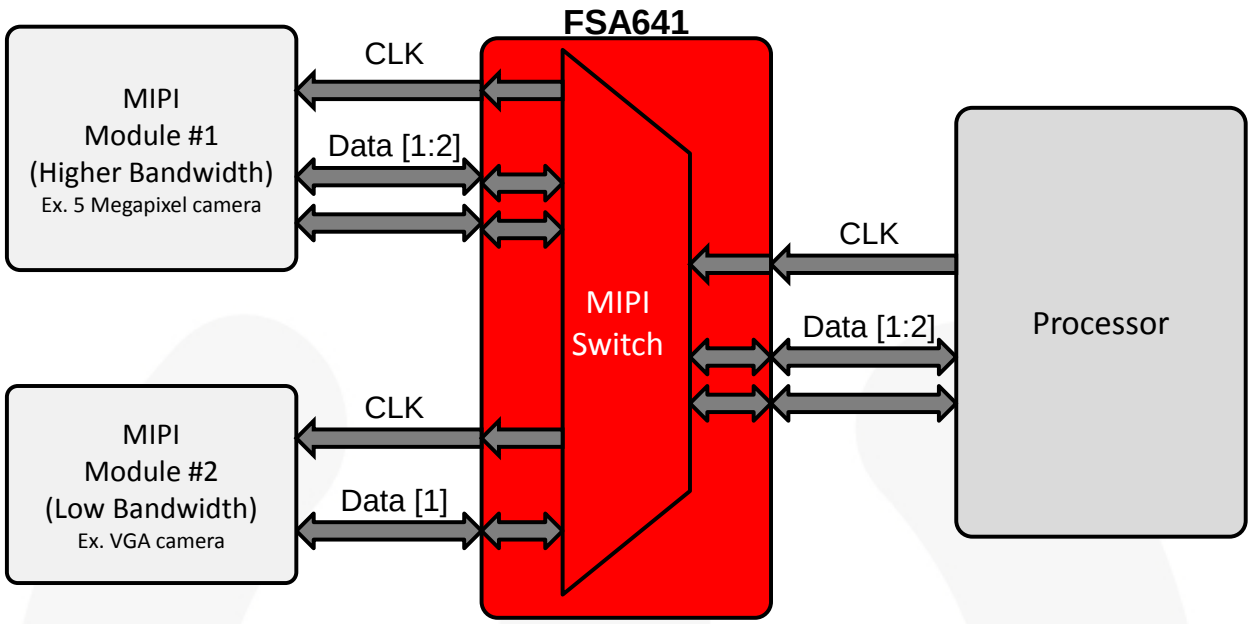


Figure 1. Mobile Phone Example

Pin Configuration

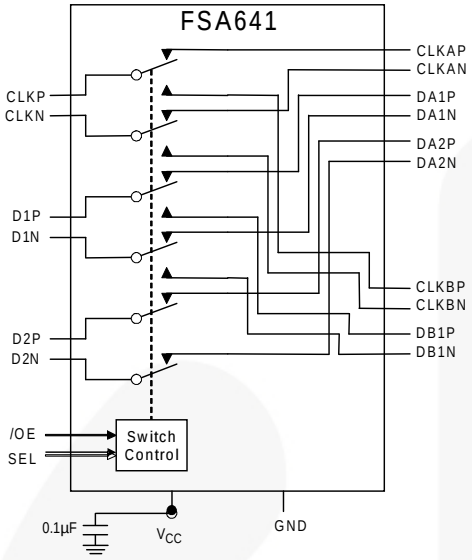


Figure 2. Functional Block Diagram

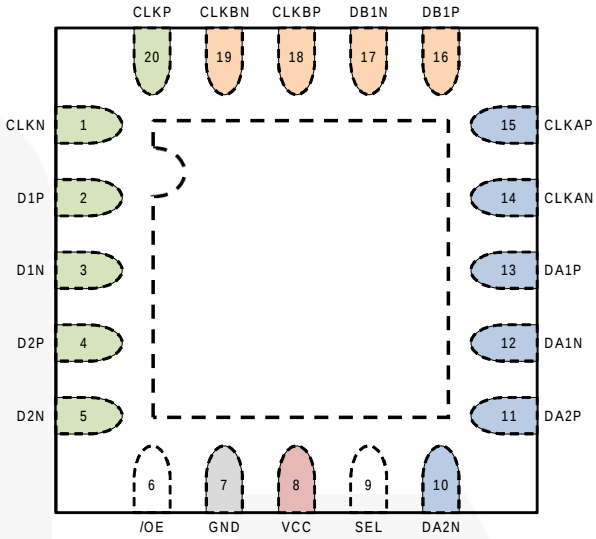


Figure 3. Pin Assignments (Top Through View)

Pin Descriptions

Pin #	Pin Name	Type	Description	
20	CLKP	I/O	Common positive clock path	
1	CLKN	I/O	Common negative clock path	
2	D1P	I/O	Common positive data 1 path	
3	D1N	I/O	Common negative data 1 path	
4	D2P	I/O	Common positive data 2 path	
5	D2N	I/O	Common negative data 2 path	
15	CLKAP	I/O	A-port positive clock path	
14	CLKAN	I/O	A-port negative clock path	
13	DA1P	I/O	A-port positive data 1 path	
12	DA1N	I/O	A-port negative data 1 path	
11	DA2P	I/O	A-port positive data 2 path	
10	DA2N	I/O	A-port negative data 2 path	
18	CLKBP	I/O	B-port positive clock path	
19	CLKBN	I/O	B-port negative clock path	
16	DB1P	I/O	B-port positive data 1 path	
17	DB1N	I/O	B-port negative data 1 path	
6	/OE	Input	Output Enable (Active Low)	
7	GND	Ground	Ground	
8	VCC	Supply	Power; 0.1 µF decoupling capacitor to ground recommended	
9	SEL	Input	A-port or B-port Select pin	0=A-port, 1= B-port
Paddle	n/a	NC	Not Connected	

Truth Table

SEL	/OE	Function
Don't Care	HIGH	Disconnect
LOW	LOW	D1, D2, CLK=DA1, DA2, CLKA
HIGH	LOW	D1, CLK=DB1, CLKB; D2 OPEN

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.50	+5.25	V
V_{CNTRL}	DC Input Voltage (SEL, /OE)[1]		-0.5	V_{CC}	V
V_{SW}	DC Switch I/O Voltage[1]		-0.5	V_{CC} + 0.3	V
I_{IK}	DC Input Diode Current		-50		mA
I_{OUT}	DC Output Current			50	mA
T_{STG}	Storage Temperature		-65	+150	°C
ESD	Human Body Model, JEDEC: JESD22-A114	All Pins		6.5	kV
		I/O to GND		8.0	
		Power to GND		16.0	
	Charged Device Model, JEDEC: JESD22-C101			2.0	

Note:

1. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	2.65	4.30	V
V_{CNTRL}	Control Input Voltage (SEL, /OE)[2]	0	V_{CC}	V
V_{SW}	Switch I/O Voltage	-0.5	V_{CC}-1 V	V
T_A	Operating Temperature	-40	+85	°C

Note:

2. The control input must be held HIGH or LOW; it must not float.

DC Electrical Characteristics

All typical values are T_A=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC} (V)	T_A=-40 to +85ºC			Units
				Min.	Typ.	Max.	
V_{IK}	Clamp Diode Voltage	I_{IN}=-18 mA	2.775			-1.2	V
I_{IN}	Control Input Leakage	V_{SW}=0 to 4.3 V	4.3	-1		1	µA
V_{IH}	Input Voltage High	V_{IN}=0 to V_{CC}	2.650 to 2.775	1.3			V
			4.3	1.7			
V_{IL}	Input Voltage Low	V_{IN}=0 to V_{CC}	2.650 to 2.775			0.5	V
I_{OZ}	Off-State Leakage	A, B=0+0.3 V to V_{CC}-0.3	4.3	-2		2	µA
I_{CC}	Quiescent Supply Current	V_{CNTRL}=0 or V_{CC}, I_{OUT}=0	4.3			1.0	µA
I_{CCT}	Increase in I_{CC} Current Per Control Voltage and V_{CC}	V_{CNTRL}=1.8 V	2.775			1.5	µA

DC Electrical Characteristics, Low-Speed Mode

All typical values are T_A=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC} (V)	T_A=-40 to +85ºC			Units
				Min.	Typ.	Max.	
R_{ON}	LS Switch On Resistance[3]	V_{SW}=1.2 V, I_{ON}=-10 mA, Figure 4	2.65		10	14	Ω
ΔR_{ON}	LS Delta R_{ON}[4]	V_{SW}=1.2 V, I_{ON}=-10 mA (Intra-pair)	2.65		0.75		Ω

Notes:

3. Measured by the voltage drop between A/B and CLK/Dn pins at the indicated current through the switch.
4. Guaranteed by characterization.

DC Electrical Characteristics, High-Speed Mode

All typical values are T_A=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC} (V)	T_A=-40 to +85ºC			Units
				Min.	Typ.	Max.	
R_{ON}	HS Switch On Resistance[5]	V_{SW}=0.4 V, I_{ON}=-10 mA, Figure 4	2.65		7.0	9.5	Ω
ΔR_{ON}	HS Delta R_{ON}[6]	V_{SW}=0.4 V, I_{ON}=-10 mA (Intra-pair)	2.65		0.75		Ω

Notes:

5. Measured by the voltage drop between A, B, and Dn pins at the indicated current through the switch.
6. Guaranteed by characterization.

AC Electrical Characteristics

All values are at R_L=50 Ω and R_S=50 Ω and all typical values are V_{CC}=2.775 V at T_A=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC} (V)	T_A=-40ºC to +85ºC			Units
				Min.	Typ.	Max.	
O_{IRR}	Off Isolation[7]	f=100 MHz, R_T=50 Ω Figure 14	2.775		-50		dB
Xtalk	Non-Adjacent Channel Crosstalk[7]	f=100 MHz, R_T=50 Ω Figure 15	2.775		-40		dB
BW	-3db Bandwidth[7]	C_L=0 pF, R_T=50 Ω Figure 13	2.775		1.0		GHz
t_{ON}	Turn-On Time SEL, /OE to Output	C_L=5 pF, V_{SW}=1.2 V Figure 6, Figure 7	2.650 to 2.775		20	37	ns
t_{OFF}	Turn-Off Time SEL, /OE to Output	C_L=5 pF, V_{SW}=1.2 V Figure 6, Figure 7	2.650 to 2.775		15	27	ns
t_{PD}	Propagation Delay[7]	C_L=5 pF Figure 6, Figure 8	2.775		0.25		ns
t_{BBM}	Break-Before-Make Time	C_L=5 pF, V_{SW1}=V_{SW2}=1.2 V Figure 12	2.650 to 2.775	7	9	12	ns

Note:

7. Guaranteed by characterization.

AC Electrical Characteristics, High-Speed

All typical values are V_{CC}=2.775 V at T_A=25°C unless otherwise specified.

Symbol	Parameter	Conditions	T_A=-40ºC to +85ºC			Units
			Min.	Typ.	Max.	
$t_{SK(Part\_Part)}$	Channel-to-Channel Skew Across Multiple Parts[8,9]	TDR-Based Method (V_{SW}-0.2V_{PP},C_L=C_{ON})		40	80	ps
$t_{SK(Chl\_Chl)}$	Channel-to-Channel Skew Within a Single Part[8]	TDR-Based Method (V_{SW}-0.2V_{PP},C_L=C_{ON})		15	30	ps
$t_{SK(Pulse)}$	Skew of Opposite Transitions in the Same Differential Channel[8]	TDR-Based Method (V_{SW}-0.2V_{PP},C_L=C_{ON})		10	20	ps

Notes:

8. Guaranteed by characterization.
9. Assumes the same V_{CC} and temperature for all devices.

Capacitance

Symbol	Parameter	Conditions	T_A=-40ºC to +85ºC			Units
			Min.	Typ.	Max.	
C_{IN}	Control Pin Input Capacitance[10]	V_{CC}=0 V		1.5		pF
C_{ON}	Dn/CLK- On Capacitance[10]	V_{CC}=2.775 V, /OE=0V, f=1 MHz Figure 11		8.0		
C_{OFF}	Dn/CLK Off Capacitance[9]	V_{CC}=2.775 V, /OE=2.775 V, f=1 MHz Figure 10		2.5		

Note:

10. Guaranteed by characterization.

Test Diagrams

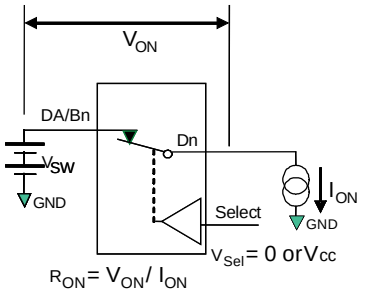
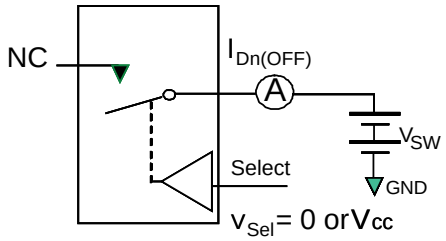
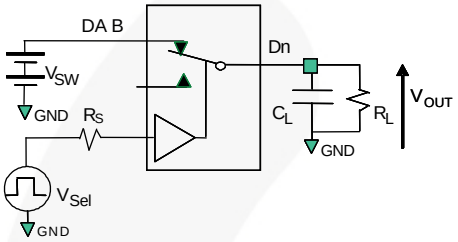


Figure 4. On Resistance



**Each switch port is tested separately

Figure 5. Off Leakage



R_L, R_S, an C_L ar fu ctions of th ap lication environment (se AC Tables for spe ific v lues)
C_L inclu es test fixture an stra capacitance

Figure 6. AC Test Circuit Load

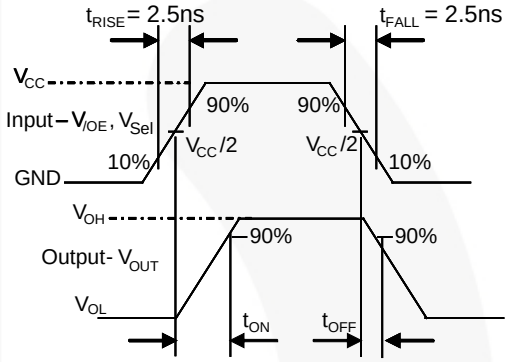


Figure 7. Turn-On / Turn-Off Waveforms

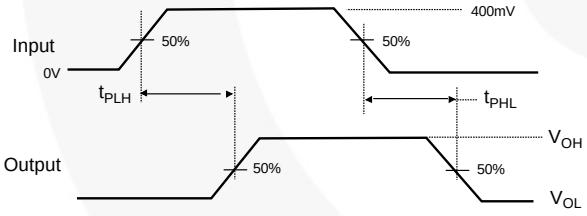


Figure 8. Propagation Delay ($t_R t_F$ – 500 ps)

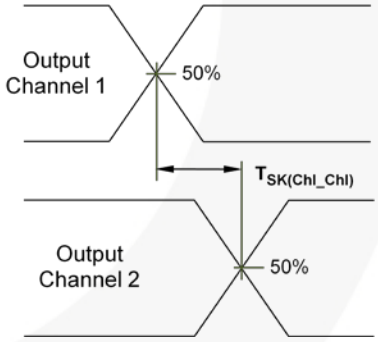


Figure 9. Channel-to-Channel Skew

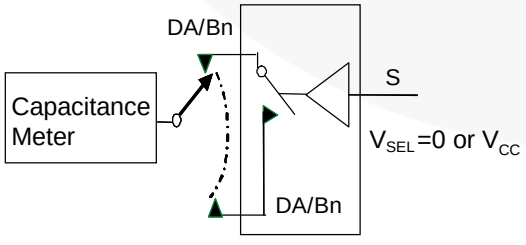


Figure 10. Channel Off Capacitance

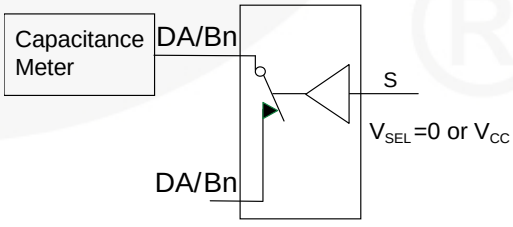
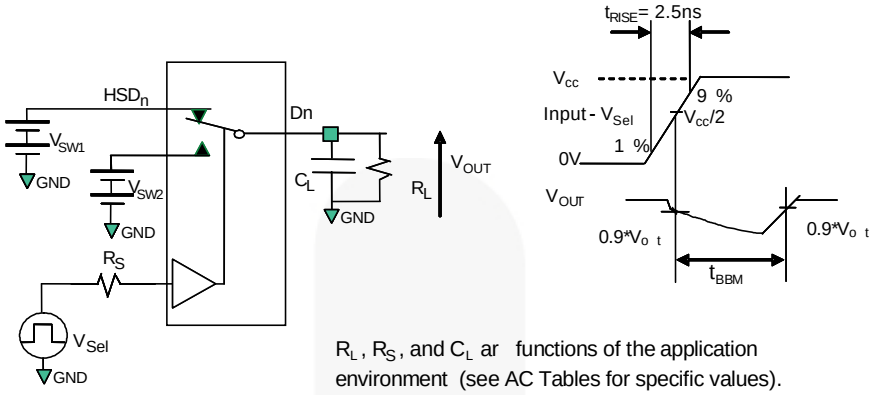


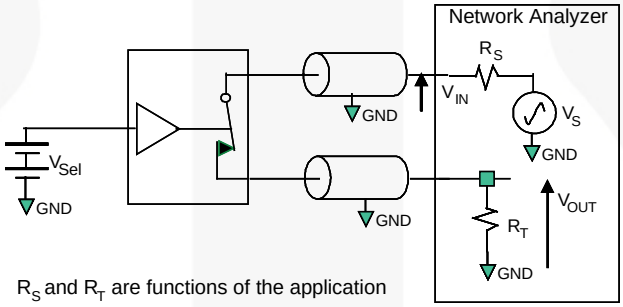
Figure 11. Channel On Capacitance

Test Diagrams (Continued)



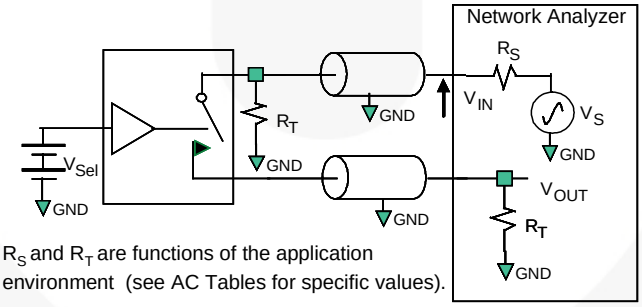
R_L, R_S, and C_L ar functions of the application environment (see AC Tables for specific values). C_L includes test fixture and stray capacitance.

Figure 12. Break-Before-Make Interval Timing



R_S and R_T are functions of the application environment (see AC Tables for specific values).

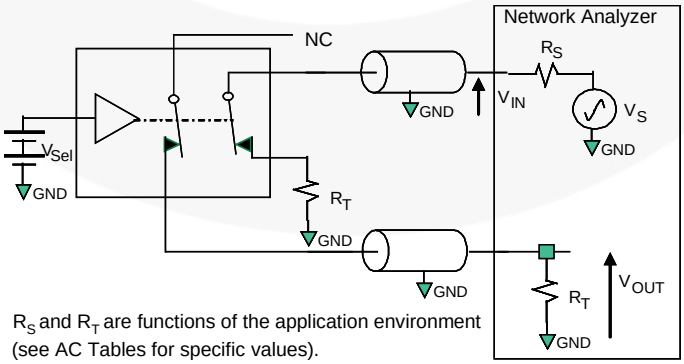
Figure 13. Bandwidth



R_S and R_T are functions of the application environment (see AC Tables for specific values).

Off isolation = 20 Log (V_{OUT} / V_{IN})

Figure 14. Channel Off Isolation



R_S and R_T are functions of the application environment (see AC Tables for specific values).

Crosstalk = 20 Log (V_{OUT} / V_{IN})

Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

Physical Dimensions

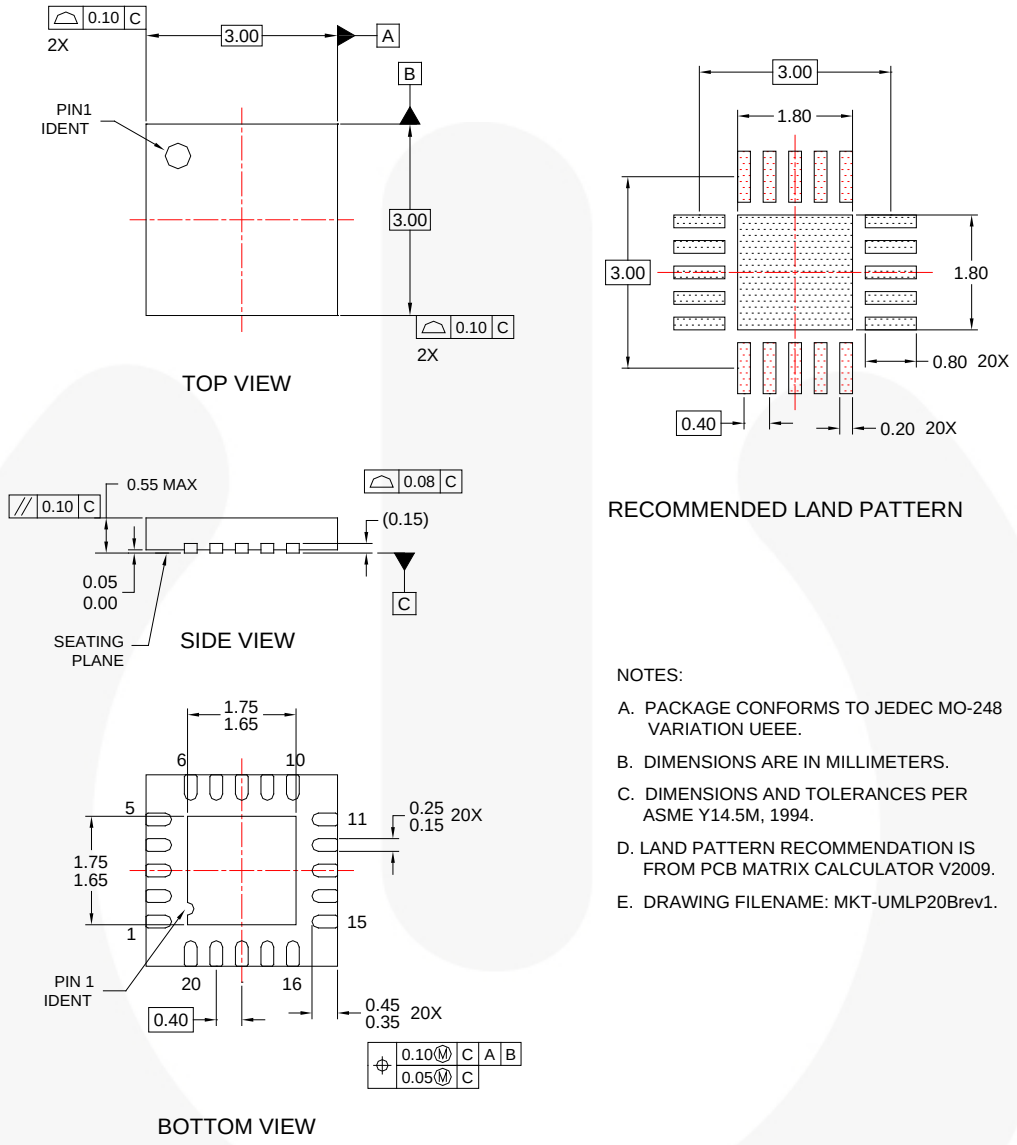


Figure 16. 20-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 3.0 x 3.0 mm

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http://www.fairchildsemi.com/dwg/UM/UMLP20B.pdf.

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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